

IPC-HERMES-9852

Version 1.4
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**The Global Standard for
Machine-to-Machine
Communication in
SMT Assembly**

Supersedes HERMES-9852, Version 1.3
May 2021

*Developed by The Hermes Standard Initiative and
approved by IPC*



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- Show relationship to Design for Manufacturability (DFM) and Design for the Environment (DFE)
- Minimize time to market
- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

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- Increase time-to-market
- Keep people out
- Increase cycle time
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- Contain anything that cannot be defended with data

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Developed by The Hermes Standard initiative and approved by IPC

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Users of this publication are encouraged to participate in the development of future revisions.

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The Global Standard for Machine-to-Machine Communication in SMT Assembly

1 SCOPE

The aim of this specification is to create a state-of-the-art communication protocol for surface-mount technology (SMT) production lines. Therefore, this new communication protocol has to cope with the following:

- Replace the electrical SMEMA interface as specified in IPC-SMEMA-9851
- Extend the interface to communicate:
 - Unique identifiers for the handled printed circuit boards (PCBs)
 - Equipment identifiers of the first machine noticing a PCB
 - Barcodes
 - Conveyor speed
 - Product type specific information:
 - Product type identifier
 - Length
 - Width
 - Thickness
 - ...

With respect to version numbers The Hermes Standard adheres to the rules of Semantic Versioning 2.0.0 [SemVer_2.0.0].

Hints on naming:

- Wherever a feature is described by the word “shall“ it is mandatory.
- The word “machine” is used for any equipment which can be found in an SMT production line (e.g., printers, placement machines, ovens, AOIs, transport modules, shuttles, stackers).
- The term “PCB” may also refer to carriers transporting PCBs
- The word “Hermes” is used as abbreviation for “The Hermes Standard”.
- “The Hermes Standard” and IPC-HERMES-9852 are synonyms for the standard specified in this document and might be used interchangeably.